Standardized Information for Process/Product Change Notification (PCN)

		1. Product Change Notif	fication [PCN	] basic data			
		Name Customer:					
Customer		Contact Email address:					
	Melexis	Site submitting the change:		Melexis leper			
1.1 Compa	INSPIRED ENGINEERING	Affected site(s):	Melexis Supplier				
1.2 PCN No.		MCM-12853					
1.3 Title of PCN		PCN: Alternative source IMC process for current sensors products [MLX91208CAL]					
1.4 Product Category		Active Components - Integrated Circuits					
1.5 Issue date		26-Oct-2021					
1.6 Note in case of Pre-Initial PCN (optional)							
1.7 PCN revision history (optional)		1.8 Issue date of previous revision (optional)	1.9 Delta to previous revision (optional)				

	2. PCN Team
2.1 Contact supplier	

2.1.1 Name	Lisa Vanheerswynghels	Lisa Vanheerswynghels		
2.1.2 Phone	+32 57 22 62 07	+32 57 22 62 07		
2.1.3 Email	pcn_mlx@melexis.com	pcn_mlx@melexis.com		
2.2 Team supplier (optional)				
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)		

	3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change	
#1	SEM-AN-01	ANY	Any change with impact on agreed upon technical contractual agreements	
#2	SEM-DS-01	DATA SHEET	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	
#3	SEM-DS-02	DATA SHEET	Correction of data sheet or issue of errata	
#4	SEM-PW-08	PROCESS - WAFER PRODUCTION	New / change of passivation or die coating (without bare die)	
#5	SEM-PW-12	PROCESS - WAFER PRODUCTION	Change of specified wafer process sequence (deletion and/or additional process step)	
#6	SEM-PW-13	PROCESS - WAFER PRODUCTION	Move all or parts of production to a different wafer fab site.	
#7	SEM-PA-13	PROCESS - ASSEMBLY	Change of product marking	
#8	SEM-EQ-01	EQUIPMENT	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	

#9	SEM-QG-01	Q-GATE	Change of the test coverage/testing process flow used by the supplier to
			ensure data sheet compliance (e.g. elimination/addition of electrical
			measurement/test flow block; relaxation/enhancement of monitoring
			procedure or sampling)

	4. Description of change			
	Old	New		
Description #1	IMC material: CoFe	IMC material: FeNi		
Description #2	Hysteresis, Remanent Field (Bop): +/- 10uT	Hysteresis, Remanent Field (Bop): +/- 15uT		
Description #3	Third row marking: YYWWHB	Third row marking: YYWWEH		
Description #4	Interface / adhesion layer: Epoxy	Interface / adhesion layer: Polyimide		
Description #5	Annealing: at raw material level	Annealing: after IMC electroplating		
Description #6	IMC Supplier: Axetris (Switzerland) IMC Supplier: XFAB-Itzehoe (Germany)			
Description #7	Third row marking: YYWWHB	Third row marking: YYWWEH		
Description #8	Glueing and etching of metal strips Electroplating			
Description #9	No Hysteresis process control at Melexis	Hysteresis Process control at Melexis: 100% hysteresis measurement at Final Test		
4.6 Anticipated impact on form, fit, function, reliability or processability?	- Based on Risk Assessment including AEC-Q100 and ZVEI guidelines			
4.7 Anticipated impact on order code	No impact, current order codes remain valid The product ordering code will not change as the products will not co-exist, the Axetris process is no longer supported in the future outside of the inventory built up at Melexis			

5. Reason / motivation for change			
5.1 Motivation	Transfer from Axetris to XFAB-Itzehoe as part of the Melexis long term product strategy and driven by End-of-Life at Axetris.		
5.2 Additional explanation (optional)	Part of Melexis long term product strategy - Automotive qualified electroplating technology at XFAB-Itzehoe - Automotive qualified annealing process at Melexis - Increased automation, standardized and state-of-the-art IMC process at XFAB-Itzehoe ready for further volume growth - Integration of front-end and back-end wafer processes at XFAB-Itzehoe - +1 Billion devices based on XFAB-Itzehoe IMC technology (magnetic position sensors, current sensors) delivered to the field		
	Timeline driven by End-of-Life Axetris - Axetris end-of-life announcement due to equipment lifetime. - Supply chain was secured during change with pre-built inventory based on customer forecast		

6. Marking of parts / traceability of change			
6.1 Description	The marking of the parts will be changed as described in detail in the attached presentation.		
	Traceability is ensured by lot number and datecode through the Melexis ERP system.		

7. Timing / schedule			
7.1 Date of qualification results	February 2022		
7.2 Last order date (optional)			
7.3 Last delivery date (optional)			
7.4 Intended start of delivery	May 2022	Please contact your Customer Relations responsible for detailed information. Note that the start of delivery can shift depending on the moment Melexis receives the customer approval.	

7.5 Qualification samples available?		
	Yes available	
	Samples can be requested throug	h pcn_mlx@melexis.com
7.6 Customer feedback required until		Please provide your initial feedback through the 'Customer Feedback' sheet as acknowledgement

8. Qualification / validation				
8.1 Description (e.g. qualification or validation plai	<ul> <li>Based on Risk Assessment including AEC-Q100</li> <li>Wide variety of automotive products qualified</li> <li>Whenever possible, re-use of Melexis qualified</li> </ul>	. Generic data avai	lable, considering automotive grade	
8.2 Qualification report and qualification results	Will be available at date:	issue date	March 2022	(expected)

9. Input to customer for ris	k assessment process
------------------------------	----------------------

See attached presentation: BOM&BOP Risk assessment

## 10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

MCM-12853 ZVEI delta qualification matrix.xlsm BOM & BOP Risk Assessment\_Axetris transfer.xlsx DIGI-KEY\_Alternative source IMC Process.pdf

11. Affected parts									
11.1 Current						11.2 New (if applicable)			
11.1.1 Customer Part No.	11.1.2 Supplier Part Name		11.1.4 Package Name	Part		11.2.2 Supplier Part Name		11.2.4 Package Name	11.2.6 Additional Part info (opt)
NA	MLX91208LDC-CAL-000-SP		SOIC8 GR						
NA	MLX91208LDC-CAL-000-TU		SOIC8 GR						